

IVMC 91

Technical Digest

The Fourth International
Vacuum Microelectronics Conference

August 22-24, 1991
Nagahama, Japan



Editors

S. Namba, Y. Nannichi, T. Utsumi

Organizing Committee of the Fourth International Vacuum Microelectronics Conference

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S. Namba, Y. Nannichi, T. Utsumi

Sponsored by

Organizing Committee of
the Fourth International Vacuum Microelectronics Conference



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PREFACE

On behalf of the local committee, we welcome all of you to the Fourth International Vacuum Microelectronics Conference (IVMC 91) to be held in Nagahama, Japan from the 22nd to the 24th, August 1991.

This digest contains extended abstracts to be presented at IVMC 91. A total of well over one hundred papers were submitted and among them 84 papers were accepted for presentation. This includes 9 invited talks, 38 oral presentations and 37 poster presentations. The last minute news, which we expect will keep arriving until the day of registration, are not included. The fact that the numbers of submitted papers have significantly increased over all previous conferences have shown the definite trend of rapidly growing interest and effort in this fascinating new field of technology all over the world. If the conference enhances our feeling that we are all comrades in making Vacuum Microelectronics a reality to open up a new frontier of science and technology and that we will be able to achieve our goals in a long run, then this conference is a great success.

We wish to express our sincere thanks to all attendees to the conference, especially to contributors who have done a tremendous job to present their works of excellence and to all attendees who are to do a superb job by participating in lively discussions during the conference.

We also wish to express our warm gratitude to the local organizing committee members for spending considerable time and effort for organizing the conference and the dedicated staff of the Secretariat of the Business Center for Academic Societies in Japan for arranging the conference.

We also wish to express our sincere gratitude to Dr. H. F. Gray of Naval Research Laboratories who assisted tremendously our local committee to organize the conference and accepted to become a guest editor of the special issue of Vacuum Microelectronics in the Journal of Vacuum Science and Technology (B) to publish the full papers of this conference.

Finally this conference could never have been realized at this level without generous financial support from the public as well as private organizations in Japan whose names are listed on page v.

We hope that all of you enjoy your stay in Nagahama and its vicinity famous for its natural beauty and its unique history in one of the most dramatic periods of Japan.

August 1991



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Chairman
Organizing
Committee
IVMC 91



Yasuo Nannichi
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Chairperson : J. Ishikawa (Kyoto Univ., Japan)

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*H. F. Gray (Naval Res. Center, U. S. A.)
J. Mitterauer (Technische Univ. Wien, Austria)
T. Utsumi (Canon, Japan)*

Opening Session

Opening Address

Keynote Speeches

COHERENCE PROPERTIES OF A FIELD EMISSION ELECTRON BEAM AND ITS APPLICATIONS

Akira TONOMURA

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1. INTRODUCTION

An electron beam field emitted from a pointed tip has a higher brightness (current density per solid angle) and a narrower energy spread than a thermal emission beam.¹⁾ In 1968, these features were effectively employed for forming a fine probe and improving the resolution limit of scanning electron microscopes by Crewe.²⁾ This beam was also used in 1978 for a "coherent" electron beam.³⁾ Using this beam, the total number of electron interference fringes recordable on film increased from 300 to more than 3,000 with an exposure time of 30 seconds, and the fringes become directly observable on the fluorescent screen.

As a result of this improvement, electron holography became practical in that its reconstructed images are comparable in resolution to electron micrographs. New application fields for electron holog-

raphy are now being opened up. For example, flux lines penetrating a superconductor can be seen in the form of magnetic lines of force in interference micrographs.⁴⁾ Their dynamics can also be observed.⁵⁾

2. ELECTRON GUN

An example of our field emission electron gun is schematically shown in Fig. 1. Electrons are emitted from a tungsten tip 1,000 Å in radius, and accelerated up to 125 kV through three-stage accelerating electrodes. Electrons are focused through condenser lenses to form a fine probe a few hundreds of Å in diameter, and illuminate a specimen.

The illumination angle can be made as small as 5×10^{-8} radians, allowing the spatial coherence length in the specimen plane to be as large as 80 μm. The spatial coherence length is the maximum diameter of the circular region within which the electron wavefront can be defined. Interference can occur within this region.

The time coherence length of an electron beam is given by $\lambda = (2E/\Delta E)$. Here, λ is the electron wavelength, E is the kinetic electron energy, and ΔE is the energy spread. When $E=100$ keV and $\Delta E=0.3$ eV, the time coherence length is around 2 μm. Interference occurs when the path difference between two beams is smaller than this length. This value seems extremely small when compared with that of a laser beam, but this is not the case. The number of wavelengths contained in this length is as large as 700,000. Usually electron interference experiments are not restricted by the time coherence length. There have been, however, two experiments in which this occurred.^{6,7)}

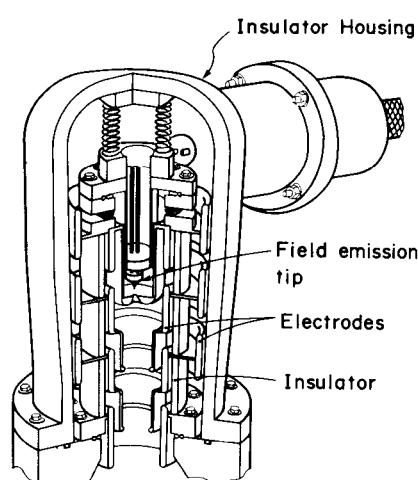


Fig. 1. Field emission electron gun.

3. ELECTRON HOLOGRAPHY

Electron holography⁸⁾ is a two-step imaging method using electron and light waves (see Fig. 2). An electron wave illuminates an object and is then scattered. A reference wave that has been tilted by a prism is then projected onto the scattered wave to form an interference pattern, which is recorded on film. This film, called a hologram, is subsequently illuminated by a collimated laser beam. The exact image is then reproduced three-dimensionally.

In holography, two images are always reconstructed. They are exactly the same except that their amplitudes are complex conjugates of each other—that is, their phase values are reversed in sign. The conjugate image is a nuisance in image observations, but it plays an important role in high-precision phase measurements. Holography imaging is unique in that it requires no lenses and uses only the most fundamental wave properties of interference and diffraction. Therefore, imaging is possible even between completely different waves. A large wavelength difference is not a problem, since interference and diffraction always take place in wavelength units.

Once electron wavefronts are reproduced as light wavefronts, versatile optical techniques can be supplemented by electron optics. One example is a holographic interference microscope. In this case, an interference micrograph, or contour map of the wavefront, can be obtained simply by combining an optical

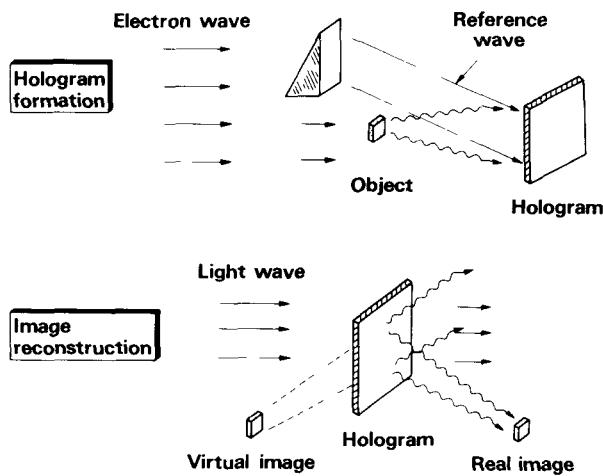


Fig. 2. Principle behind electron holography.

interferometer in the optical reconstruction stage. This is done by overlapping an optical plane wave with the reconstructed image. If a conjugate image instead of a plane wave overlaps this wavefront, the phase difference becomes twice as large, as if the phase distribution were amplified two times. By repeating this technique, a phase shift even as small as $1/100$ of a wavelength can be detected.

Phase-amplified interference electron microscopy provides information about a specimen's thickness distribution in atomic dimensions⁹⁾ and microscopic distribution of the electric¹⁰⁾ and magnetic¹¹⁾ fields.

4. APPLICATIONS

a) Specimen thickness measurements:
An interference micrograph amplified 24 times of a cleaved molybdenite thin film is shown in Fig. 3. The phase distribution is displayed here as a deviation from regular fringes, i. e., an interferogram. Steps A, B, and C in the micrograph correspond to one, three, and five layers of atomic surface steps. The thickness change at step A is 6.2 \AA (one-half of the c-axis spacing), and produces a phase shift of $2\pi/50$. This experiment shows that a phase shift can be detected with an accuracy of the order of $2\pi/100$.

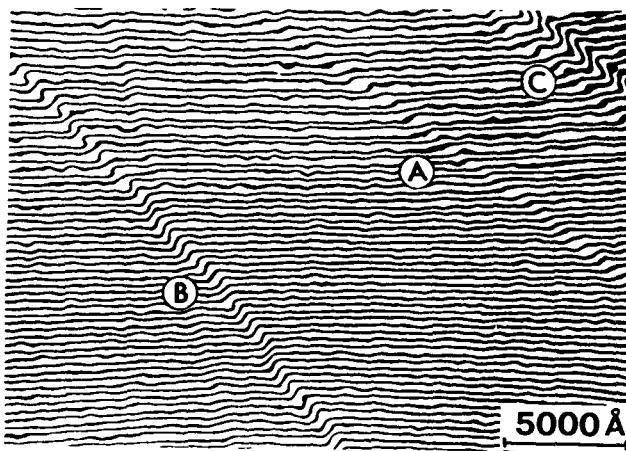


Fig. 3. Interferogram of molybdenite thin film (phase amplification: $\times 24$).